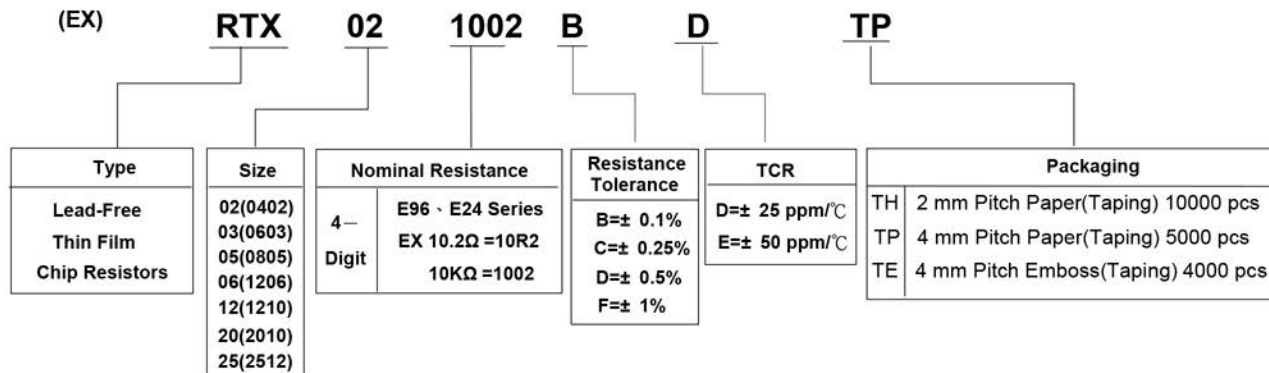


1 Scope:

This specification is applicable to lead and halogen free RTX series thin film chip resistors.

2 Explanation Of Part Numbers:



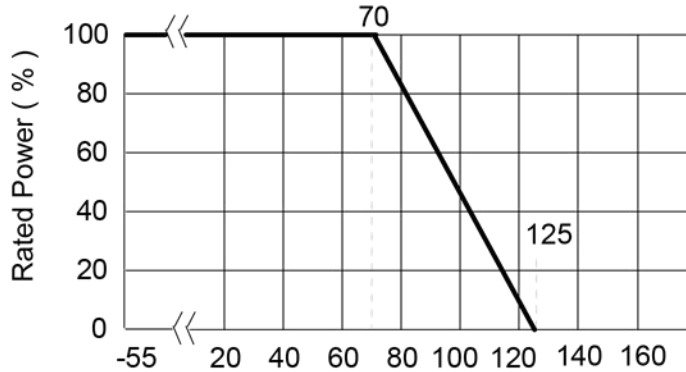
3 General Specifications:

Type	Rated Power at 70°C	Max. Working Voltage	Max. Overload Voltage	T.C.R. (ppm/°C)	Resistance Range			
					B(± 0.1%) E-96 · E24	C(± 0.25%) E-96 · E24	D(± 0.5%) E-96 · E24	F(± 1%) E-96 · E24
RTX02	$\frac{1}{16}$ W	50V	100V	± 25	10Ω ~ 121KΩ			
				± 50				
RTX03	$\frac{1}{10}$ W	75V	150V	± 25	10Ω ~ 681KΩ			
				± 50				
RTX05	$\frac{1}{8}$ W	150V	300V	± 25	10Ω ~ 1.5MΩ			
				± 50				
RTX06	$\frac{1}{8}$ W	200V	400V	± 25	10Ω ~ 1.5MΩ			
				± 50				
RTX12	$\frac{1}{4}$ W	200V	400V	± 25	10Ω ~ 1MΩ			
				± 50				
RTX20	$\frac{1}{2}$ W	200V	400V	± 25	10Ω ~ 1MΩ			
				± 50				
RTX25	$\frac{3}{4}$ W	200V	400V	± 25	10Ω ~ 1MΩ			
				± 50				
Operating Temperature Range				-55°C ~ +125°C				

3.1 Power Derating Curve:

Operating Temperature Range : -55°C ~ 125°C

For resistors operated in ambient temperatures above 70°C , power rating shall be derated in accordance with figure below.



3.2 Voltage Rating:

Rated Voltage: The resistor shall have a DC continuous working voltage or a rms. AC continuous working voltage at commercial-line frequency and wave form corresponding to the power rating, as determined from the following:

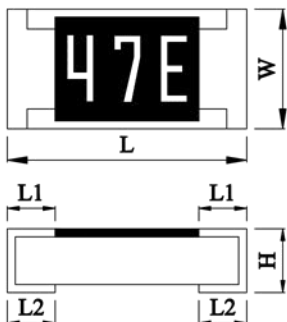
$$E = \sqrt{R \times P}$$

E= Rated voltage (v)

P= Power rating (w)

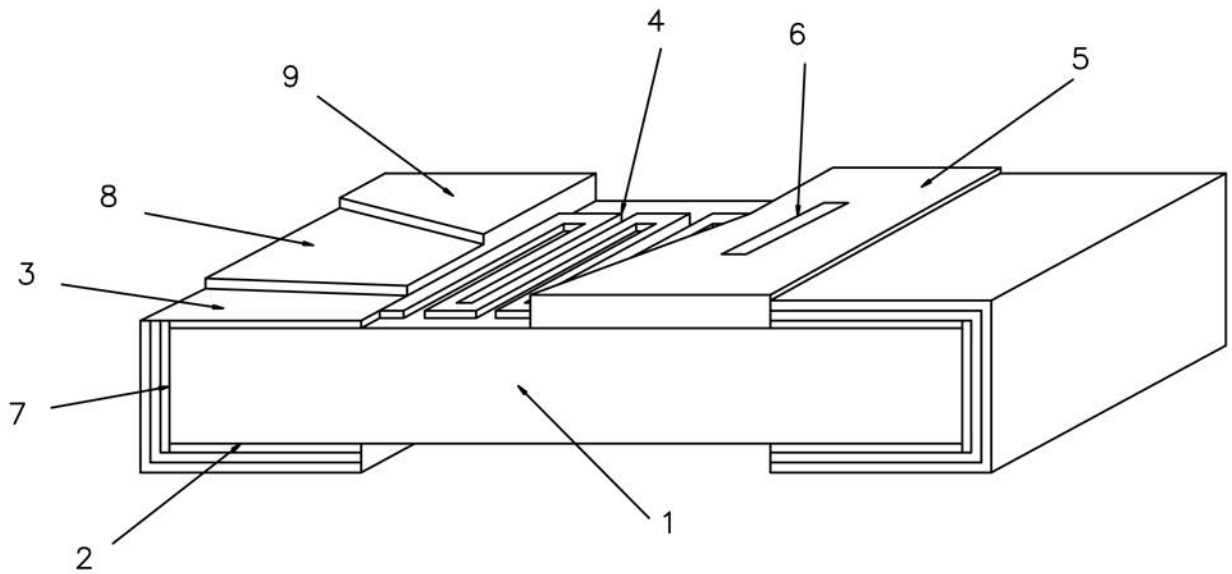
R= Nominal resistance(Ω)

4 Dimensions:



Dimensions		L	W	H	L1	L2
TYPE	Size Code					
RTX02	0402	1.00± 0.10	0.50± 0.05	0.30± 0.05	0.20± 0.10	0.25± 0.10
RTX03	0603	1.60± 0.10	0.80± 0.10	0.45± 0.10	0.30± 0.15	0.30± 0.15
RTX05	0805	2.00± 0.10	1.25± 0.10	0.50± 0.10	0.35± 0.20	0.35± 0.15
RTX06	1206	3.05± 0.10	1.55± 0.10	0.55 ^{+0.10} _{-0.05}	0.45± 0.20	0.35± 0.15
RTX12	1210	3.05± 0.10	2.55± 0.10	0.55± 0.10	0.50± 0.20	0.50± 0.20
RTX20	2010	5.00± 0.20	2.50± 0.20	0.55± 0.10	0.60± 0.20	0.60± 0.20
RTX25	2512	6.30± 0.20	3.20± 0.20	0.55± 0.10	0.60± 0.20	0.60± 0.20

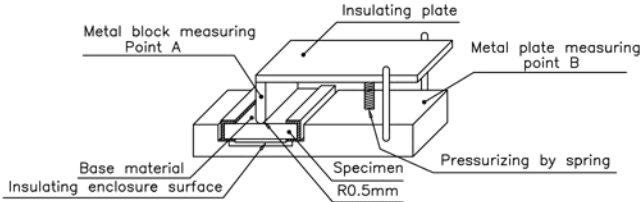
5 Structure Graph:



1	Ceramic substrate	6	Marking
2	Bottom inner electrode	7	Terminal inner electrode
3	Top inner electrode	8	Ni plating
4	Resistive layer	9	Sn plating
5	Protective coating		

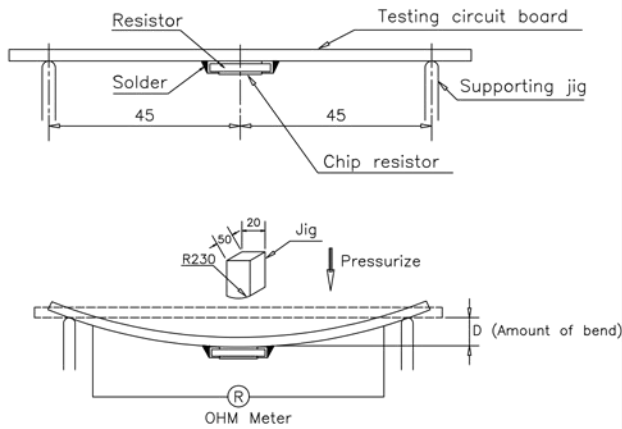
6 Reliability Test

6.1 Electrical Performance Test

ITEM	Conditions	Specifications																
		Resistors																
Temperature Coefficient of Resistance	$TCR \text{ (ppm/}^\circ\text{C)} = \frac{R_2 - R_1}{R_1 (T_2 - T_1)} \times 10^6$ R1: Resistance at room temperature R2: Resistance at -55°C or +125°C T1: Room temperature T2: Temperature -55°C or +125°C Refer to JIS-C5201-1 4.8	Refer to item 3. general specifications																
Short Time Overload	Applied 2.5 times rated voltage for 5 seconds and release the load for about 30 minutes , then measure its resistance variance rate. (Rated voltage refer to item 3. general specifications) Refer to JIS-C5201-1 4.13	± (0.5% + 0.05 Ω)																
		No evidence of mechanical damage.																
Insulation Resistance	Put the resistor in the fixture, add 100 VDC in + , - terminal for 60 sec then measured the insulation resistance between electrodes and insulating enclosure or between electrodes and base material. Refer to JIS-C5201-1 4.6	≥ 10 ⁹ Ω																
																		
Dielectric Withstand Voltage	Put the resistor in the fixture, add VAC (see SPEC below) in +, - terminal for. RTX02 · 03 apply 300 VAC 1 minute. RTX05 · 06 · 12 · 20 · 25 apply 500 VAC 1 minute. Refer to JIS-C5201-1 4.7	No short or burned on the appearance.																
Intermittent Overload	Put the tested resistor in chamber under temperature 25± 2°C and load the rated DC voltage for 1 sec on , 25 sec off , 10000 ⁺⁴⁰⁰ ₀ test cycles, then it be left at no-load for 1 hour ,then measure its resistance variance rate. Refer to JIS-C5201-1 4.13	± (0.5% + 0.05 Ω)																
Noise Level	Refer to JIS-C5201-1 4.12	<table border="1"> <thead> <tr> <th>Resistance</th> <th>Noise</th> </tr> </thead> <tbody> <tr> <td>R < 100 Ω</td> <td>≤ -10db(0.32 uV/V)</td> </tr> <tr> <td>100 Ω ≤ R < 1K Ω</td> <td>≤ 0db(1.0 uV/V)</td> </tr> <tr> <td>1K Ω ≤ R < 10K Ω</td> <td>≤ 10db(3.2 uV/V)</td> </tr> <tr> <td>10K Ω ≤ R < 100K Ω</td> <td>≤ 15db(5.6 uV/V)</td> </tr> <tr> <td>100K Ω ≤ R < 1M Ω</td> <td>≤ 20db(10 uV/V)</td> </tr> <tr> <td>1M Ω ≤ R</td> <td>≤ 30db(32 uV/V)</td> </tr> </tbody> </table>			Resistance	Noise	R < 100 Ω	≤ -10db(0.32 uV/V)	100 Ω ≤ R < 1K Ω	≤ 0db(1.0 uV/V)	1K Ω ≤ R < 10K Ω	≤ 10db(3.2 uV/V)	10K Ω ≤ R < 100K Ω	≤ 15db(5.6 uV/V)	100K Ω ≤ R < 1M Ω	≤ 20db(10 uV/V)	1M Ω ≤ R	≤ 30db(32 uV/V)
		Resistance	Noise															
R < 100 Ω	≤ -10db(0.32 uV/V)																	
100 Ω ≤ R < 1K Ω	≤ 0db(1.0 uV/V)																	
1K Ω ≤ R < 10K Ω	≤ 10db(3.2 uV/V)																	
10K Ω ≤ R < 100K Ω	≤ 15db(5.6 uV/V)																	
100K Ω ≤ R < 1M Ω	≤ 20db(10 uV/V)																	
1M Ω ≤ R	≤ 30db(32 uV/V)																	

6.2 Mechanical Performance Test

ITEM	Conditions	Specifications														
		Resistors														
Core Body Strength	Applied test probe at its central part then pushing 10N { 1.02 Kgf } force on the sample for 10 sec. 1.RTX02、03 : probe R0.2 2.RTX05、06、12、20、25 : probe R0.5 Refer to JIS-C5201-1 4.15	$\pm (0.5\% + 0.05\Omega)$ No evidence of mechanical damage. No side conductive peel off.														
Terminal strength	Test1:The resistor mounted on the board applied 5N pushing force on the sample rear for 10 sec. Test2:The resistor mounted on the board slowly add force on the sample rear until the sample termination is breakdown. Refer to JIS-C5201-1 4.16	Test1: No evidence of mechanical damage. Test2: $\geq 5N$														
Resistance to solvent	The tested resistor be immersed into isopropyl alcohol of 20~25°C for 5 \pm 0.5 min, then the resistor is left in the room for 48 hr, and measured its resistance variance rate. Refer to JIS-C5201-1 4.29	$\pm (0.5\% + 0.05\Omega)$ No evidence of mechanical damage, no G2 overcoating and Sn layer by leaching.														
Solderability	Preconditioning Put the tested resistor in the apparatus of PCT, at a temperature of 105°C, humidity of 100% RH, and pressure of 1.22 \times 10 ⁵ Pa for a duration of 4 hours. Then after left the tested resistor in room temperature for 2 hours or more. Test method: ◎Test item1 (solder pot test): The resistor be immersed into solder pot in temperature 235 \pm 3°C for 2 \pm 0.5 sec, then the resistor is left as placed under microscope to observed its solder area. ◎Test item2 (wetting balance method): Add flux into resistors, then put resistor into wetting balance machine, refer to condition as below, then must be measured and recorded its time changed. <table border="1" data-bbox="229 1289 892 1613"> <thead> <tr> <th colspan="2">Testing conditions for wetting balance method with solder pot</th> </tr> <tr> <th></th> <th>Condition</th> </tr> </thead> <tbody> <tr> <td>Solder temperature</td> <td>235\pm 3°C</td> </tr> <tr> <td>Immersion speed</td> <td>1 to 5 mm/s</td> </tr> <tr> <td>Immersion depth</td> <td>0.10 mm</td> </tr> <tr> <td>Immersion angle</td> <td>Horizontal</td> </tr> <tr> <td>Mass of solder ball</td> <td>25mg →0402、0603 200mg →0805、1206、1210、2010、2512</td> </tr> </tbody> </table> Refer to JIS-C5201-1 4.17	Testing conditions for wetting balance method with solder pot			Condition	Solder temperature	235 \pm 3°C	Immersion speed	1 to 5 mm/s	Immersion depth	0.10 mm	Immersion angle	Horizontal	Mass of solder ball	25mg →0402、0603 200mg →0805、1206、1210、2010、2512	1.Test item 1: Solder coverage over 95% 2.Test item 2: Zero cross time within 3 seconds.
Testing conditions for wetting balance method with solder pot																
	Condition															
Solder temperature	235 \pm 3°C															
Immersion speed	1 to 5 mm/s															
Immersion depth	0.10 mm															
Immersion angle	Horizontal															
Mass of solder ball	25mg →0402、0603 200mg →0805、1206、1210、2010、2512															

ITEM	Conditions	Specifications
		Resistors
Resistance to soldering heat	The tested resistor be immersed into molten solder of $260 \pm 5^\circ\text{C}$ for 10 seconds. Then the resistor is left in the room for 1 hour. Refer to JIS-C5201-1 4.18	$\pm (0.5\%+0.05\Omega)$ No evidence of electrode damage. No side conductive peel off.
Bending Test	Solder tested resistor on to PC board. add force in the middle down , and under load measured its resistance variance rate. D: RTX02 、03 、05=5mm RTX06 、12=3mm RTX20 、25=2mm 	$\pm (0.5\%+0.05\Omega)$ No evidence of mechanical damage. No terminal peel off and core body cracked.
Leaching Test	The tested resistor be immersed into molten solder of $260 \pm 5^\circ\text{C}$ for 30 seconds. Then the resistor is left as placed under microscope to observed its solder area.	1.Solder coverage over 95%. 2.The underlying material (such as ceramic) shall not be visible at the crest corner area of the electrode.
Vibration	The resistor shall be mounted by its terminal leads to the supporting terminals on the solid table. The entire frequency range :from 10 Hz to 55 Hz and return to 10 Hz, shall be transferred in 1 min. Amplitude :1.5 mm This motion shall be applied for a period of 2 hours in each 3 mutually perpendicular directions (a total of 6 hr) Refer to JIS-C5201-1 4.22	$\pm (0.5\%+0.05\Omega)$ No evidence of mechanical damage.

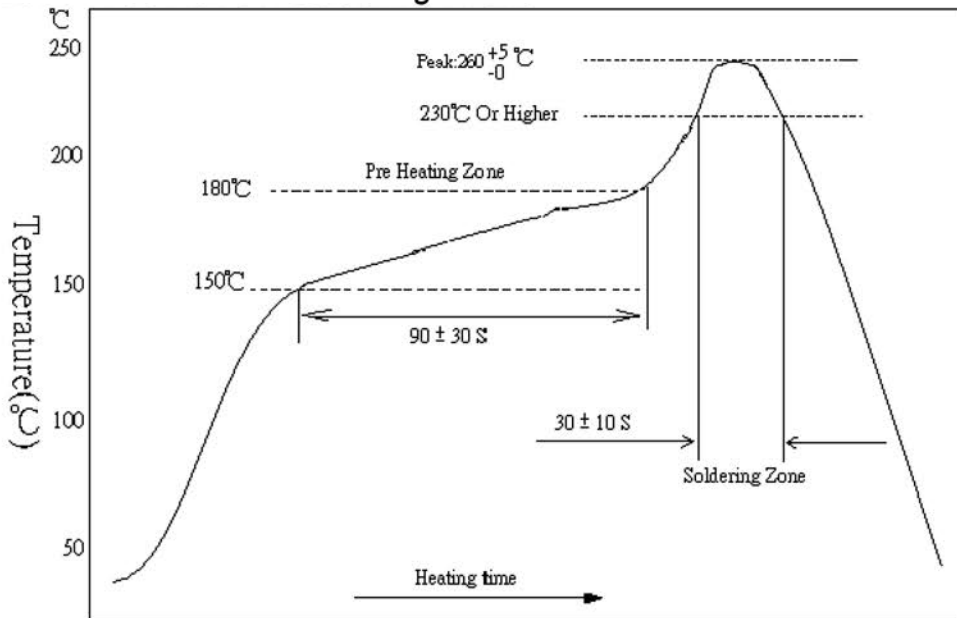
5.3 Environmental Test

ITEM	Conditions	Specifications								
		Resistors								
Resistance to Dry Heat	Put tested resistor in chamber under temperature $125 \pm 5^\circ\text{C}$ for 1000 +48/-0 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25	$\pm (0.5\% + 0.05\Omega)$								
		No evidence of mechanical damage.								
Thermal Shock	Put the tested resistor in the thermal shock chamber under the temperature cycle which shown in the following table shall be repeated 300 times consecutively. Then leaving the tested resistor in the room temperature for 1 hours, and measure its resistance variance rate. <table border="1" data-bbox="278 668 892 858"> <thead> <tr> <th></th> <th>Testing Condition</th> </tr> </thead> <tbody> <tr> <td>Lowest Temperature</td> <td>$-55 \pm 5^\circ\text{C}$</td> </tr> <tr> <td>Highest Temperature</td> <td>$125 \pm 5^\circ\text{C}$</td> </tr> <tr> <td>Temperature-retaining time</td> <td>15 minutes each</td> </tr> </tbody> </table>		Testing Condition	Lowest Temperature	$-55 \pm 5^\circ\text{C}$	Highest Temperature	$125 \pm 5^\circ\text{C}$	Temperature-retaining time	15 minutes each	$\pm (0.5\% + 0.05\Omega)$
			Testing Condition							
Lowest Temperature	$-55 \pm 5^\circ\text{C}$									
Highest Temperature	$125 \pm 5^\circ\text{C}$									
Temperature-retaining time	15 minutes each									
	Refer to MIL-STD 202 Method 107	No evidence of mechanical damage.								
Loading Life in Moisture	Put the tested resistor in the chamber under temperature $40 \pm 2^\circ\text{C}$, relative humidity 90~95% and load the rated voltage for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.24	$\pm (0.5\% + 0.05\Omega)$								
		No evidence of mechanical damage.								
Load Life	Put the tested resistor in chamber under temperature $70 \pm 2^\circ\text{C}$ and load the rated voltage for 90 minutes on, 30 minutes off, total 1000 hours. Then leaving the tested resistor in room temperature for 60 minutes, and measure its resistance variance rate. Refer to JIS-C5201-1 4.25	$\pm (0.5\% + 0.05\Omega)$								
		No evidence of mechanical damage.								
Low Temperature Operation	Put the tested resistor in the chamber at room temperature 25°C . Decreasing the temperature to -55°C and keep the temperature at -55°C for 1 hour. Then load the rated voltage for 45 minutes on, and 15 minutes off. Then leaving the tested resistor in room temperature for 8 ± 1 hours, and measure its resistance variance rate. Refer to MIL-R-55342D 4.7.4	$\pm (0.5\% + 0.05\Omega)$								
		No evidence of mechanical damage.								
Whisker Test	◎Test item 1 (Thermal Shock test): <table border="1" data-bbox="278 1540 892 1720"> <tbody> <tr> <td>Minimum storage temperature</td> <td>$-40 \pm 2^\circ\text{C}$</td> </tr> <tr> <td>Maximum storage temperature</td> <td>$85 \pm 2^\circ\text{C}$</td> </tr> <tr> <td>Temperature-retaining time</td> <td>7 min.</td> </tr> <tr> <td>Number of temperature cycles</td> <td>1,500</td> </tr> </tbody> </table>	Minimum storage temperature	$-40 \pm 2^\circ\text{C}$	Maximum storage temperature	$85 \pm 2^\circ\text{C}$	Temperature-retaining time	7 min.	Number of temperature cycles	1,500	Max. 50 μm
	Minimum storage temperature	$-40 \pm 2^\circ\text{C}$								
Maximum storage temperature	$85 \pm 2^\circ\text{C}$									
Temperature-retaining time	7 min.									
Number of temperature cycles	1,500									

ITEM	Conditions	Specifications						
		Resistors						
	<p>◎ Test item 2 (Constant temperature/humidity test):</p> <table border="1"> <tr> <td>Temperature</td> <td>85°C</td> </tr> <tr> <td>Humidity</td> <td>85%</td> </tr> <tr> <td>Testing duration</td> <td>500± 4 hours</td> </tr> </table> <p>◎ Inspection: Inspect for whisker formation on specimens that underwent the acceleration test specified in subclause 4.2, with a magnifier (stereo microscope) of about 40 or higher magnification. If judgment is hard in this method, use a scanning electron microscope (SEM) of about 1,000 or higher magnification.</p>	Temperature	85°C	Humidity	85%	Testing duration	500± 4 hours	
Temperature	85°C							
Humidity	85%							
Testing duration	500± 4 hours							

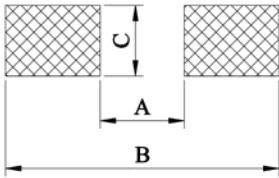
7 Recommend Soldering Method

7.1 Lead Free Reflow Soldering Profile



7.2 Soldering Iron: temperature $350^{\circ}\text{C} \pm 10^{\circ}\text{C}$, dwell time shall be less than 3 sec.

8 Recommend Land Pattern Design (For Reflow Soldering) : (mm)



DIM	A	B	C
TYPE			
RTX02	0.5	1.5	0.6
RTX03	0.8	2.1	0.9
RTX05	1.2	3.0	1.3
RTX06	2.2	4.2	1.6
RTX12	2.2	4.2	2.8
RTX20	3.5	6.1	2.8
RTX25	3.8	8.0	3.5

9 Marking Diagrams:

9.1 RTX05、06、12、20、25 ± 0.1%、± 0.25%、± 0.5%、± 1% Tolerance:

9.1.1.1 Resistance Range $\geq 100 \Omega$: 4 digits in E-24 series or E-96 series, first three digits are significant figures, fourth digit is multiplier (10^x).

《EX》 Marking → 1002

$$1002 = 100 \times 10^2 = 10000 \Omega = 10K \Omega$$

9.1.1.2 Resistance Range $< 100 \Omega$: 4 digits in E-24 series or E-96 series, three digits are significant figures, R digit is multiplier (10^x).

《EX》 Marking → 10R2 ,R digit is multiplier (10^{-1}).

$$10R2 = 102 \times 10^{-1} = 10.2 \Omega$$

Marking → 1R02 ,R digit is multiplier (10^{-2}).

$$1R02 = 102 \times 10^{-2} = 1.02 \Omega$$

9.2 RTX03 ± 0.1%、± 0.25%、± 0.5%、± 1% Tolerance:

For EIAJ-96 Marking.

《EX》 Marking → 47B

$$47B = 301 \times 10^1 = 3010 \Omega = 3.01K \Omega$$

If the resistance is not in E-96 series and in E-24 series, the marking is expressed by E-24 series and one short bar under marking letter.

R value $> 100 \Omega$: marking 391 391 = $39 \times 10^1 = 390 \Omega$

R value $< 100 \Omega$: marking 390 390 = $39 \times 10^0 = 39 \Omega$

9.3 RTX02 No Marking

9.4 EIAJ-96 Marking:

This table shows the first two digits for the three-digits EIAJ-96 part marking scheme. The third character is a letter multiplier:

Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω	Code	Ω
01	100	13	133	25	178	37	237	49	316	61	422	73	562	85	750
02	102	14	137	26	182	38	243	50	324	62	432	74	576	86	768
03	105	15	140	27	187	39	249	51	332	63	442	75	590	87	787
04	107	16	143	28	191	40	255	52	340	64	453	76	604	88	806
05	110	17	147	29	196	41	261	53	348	65	464	77	619	89	825
06	113	18	150	30	200	42	267	54	357	66	475	78	634	90	845
07	115	19	154	31	205	43	274	55	365	67	487	79	649	91	866
08	118	20	158	32	210	44	280	56	374	68	499	80	665	92	887
09	121	21	162	33	215	45	287	57	383	69	511	81	681	93	909
10	124	22	165	34	221	46	294	58	392	70	523	82	698	94	931
11	127	23	169	35	226	47	301	59	402	71	536	83	715	95	953
12	130	24	174	36	232	48	309	60	412	72	549	84	732	96	976

Y = 10^{-2} X = 10^{-1} A = 10^0 B = 10^1 C = 10^2 D = 10^3 E = 10^4 F = 10^5

10 Plating Thickness:

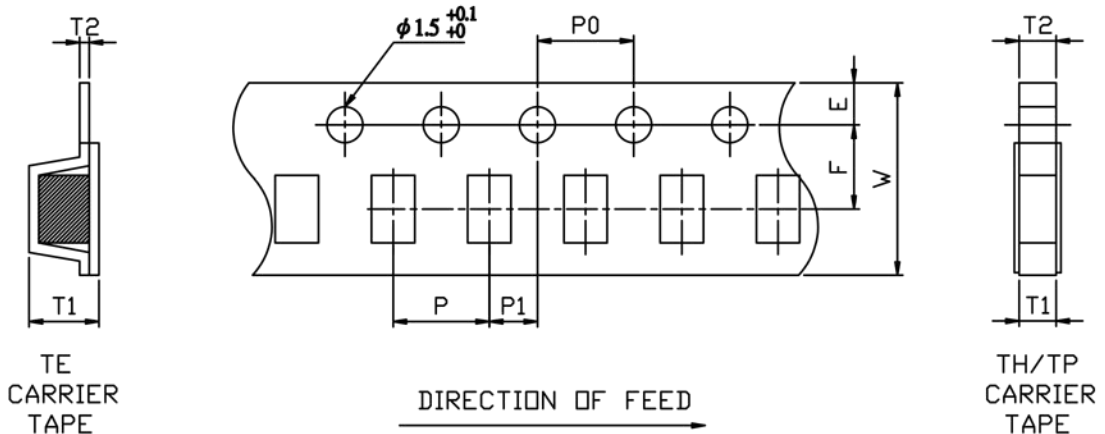
10.1Ni: $\geq 1 \mu m$

10.2Sn(Tin): $\geq 3 \mu m$

10.3Sn(Tin): Matte Sn

11 Taping Specifications:

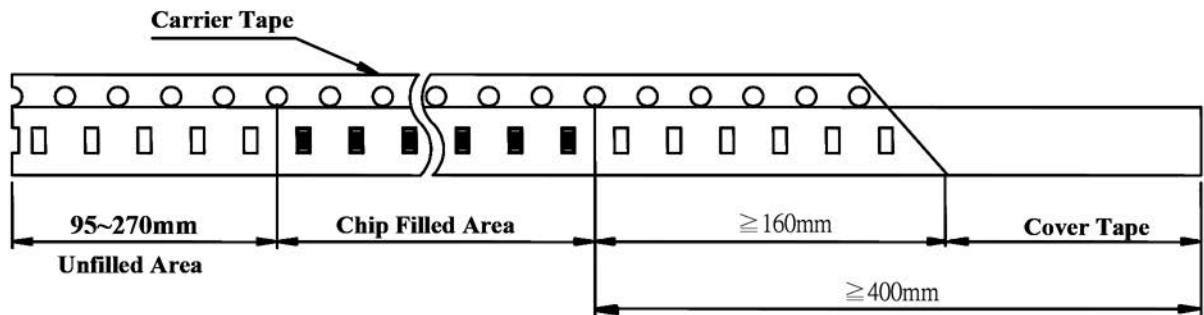
11.1 Tape Dimension



Unit: mm

Packaging	DIM	A	B	W	E	F	T1	T2	P	P0	10× P0	P1
	TYPE											
TH Carrier Tape	RTX02	1.15± 0.05	0.65± 0.05	8.0± 0.2	1.75± 0.1	3.5± 0.05	0.45+0.2/-0	0.45± 0.05	2.0± 0.1	4.0± 0.05	40.0± 0.2	2.0± 0.05
TP Carrier Tape	RTX03	1.80± 0.1	1.00± 0.1	8.0± 0.2	1.75± 0.1	3.5± 0.05	0.60+0.2/-0	0.60± 0.1	4.0± 0.1	4.0± 0.05	40.0± 0.20	2.0± 0.05
	RTX05	2.40± 0.10	1.65± 0.10	8.0± 0.20	1.75± 0.10	3.5± 0.05	0.75+0.2/-0	0.75± 0.10	4.0± 0.10	4.0± 0.05	40.0± 0.20	2.0± 0.05
	RTX06	2.30± 0.1	1.55± 0.1	8.0± 0.2	1.75± 0.1	3.5± 0.05	0.75+0.2/-0	0.75± 0.1	4.0± 0.1	4.0± 0.05	40.0± 0.20	2.0± 0.05
	RTX12	3.50± 0.2	1.90± 0.2	8.0± 0.2	1.75± 0.1	3.5± 0.05	0.75+0.2/-0	0.75± 0.1	4.0± 0.1	4.0± 0.05	40.0± 0.20	2.0± 0.05
TE Carrier Tape	RTX20	5.50± 0.2	2.80± 0.2	12.0± 0.2	1.75± 0.1	5.5± 0.05	0.85± 0.15	0.23± 0.15	4.0± 0.1	4.0± 0.05	40.0± 0.20	2.0± 0.05
	RTX25	6.70± 0.2	3.40± 0.2	12.0± 0.2	1.75± 0.1	5.5± 0.05	0.85± 0.15	0.23± 0.15	4.0± 0.1	4.0± 0.05	40.0± 0.20	2.0± 0.05

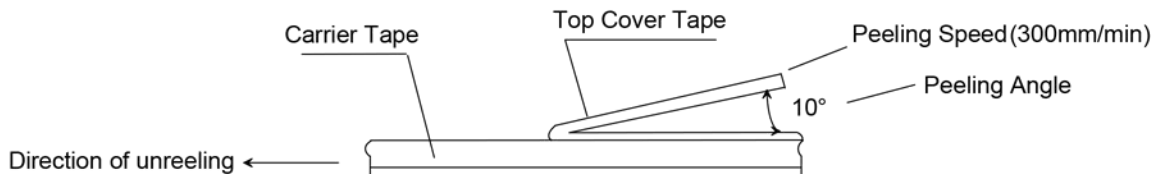
11.2 Lead Dimensions:



11.3 Cover Tape Peel off Strength

Specifications: 0402 => 0.07~0.5N (7.1~51gf)

0603、0805、1206、1210、2010、2512=> 0.07~0.7N (7.1~71.4gf)



11.4 Packaging QTY:

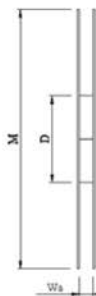
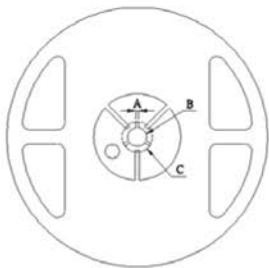
TYPE	Tape Width	Packaging QTY (pcs/reel)											
		Paper								Plastic			
		2 mm Pitch				4 mm Pitch				4 mm Pitch			
		TH	H2	H3	H4	TP	P2	P3	P4	TE	E2	E3	E4
RTX02	8 mm	10,000	20,000	30,000	40,000	--	--	--	--	--	--	--	--
RTX03	8 mm												
RTX05	8 mm												
RTX06	8 mm	--	--	--	--	5,000	10,000	15,000	20,000	--	--	--	--
RTX12	8 mm												
RTX20	12 mm												
RTX25	12 mm	--	--	--	--	--	--	--	--	4,000	8,000	12,000	16,000
Reel Type		7"	10"	13"	13"	7"	10"	13"	13"	7"	10"	13"	13"

11.4.1 Typical taping type: TH · TP · TE

11.4.2 Other taping type are upon customer's request.

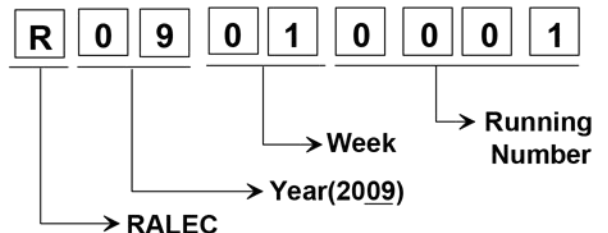
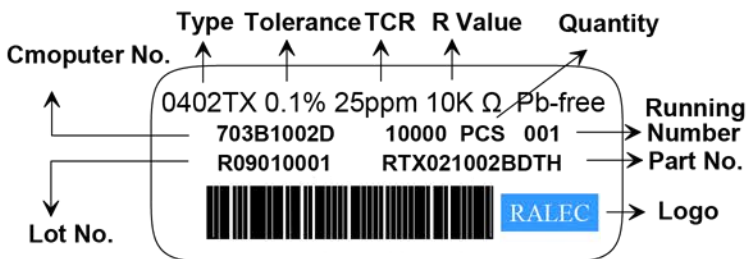
11.5 Reel Dimensions:

Unit:mm



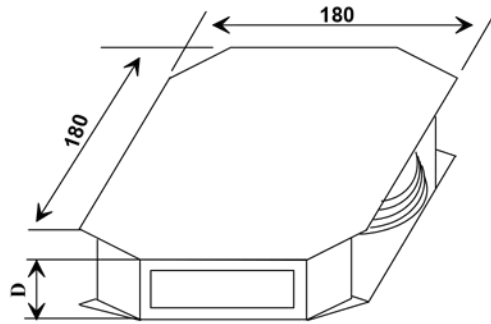
Reel Type/ Tape	Wa	M	A	B	C	D
7" reel for 8 mm tape	9.0 ± 0.5	178 ± 2.0				60.0 ± 1.0
7" reel for 12 mm tape	13.8 ± 0.5	178 ± 2.0	2.0 ± 0.5	13.5 ± 0.5	21.0 ± 0.5	80.0 ± 1.0
10" reel for 8 mm tape	10.0 ± 0.5	254 ± 2.0				100.0 ± 1.0
13" reel for 8 mm tape	10.0 ± 0.5	330 ± 2.0				100.0 ± 1.0

11.6 Label:



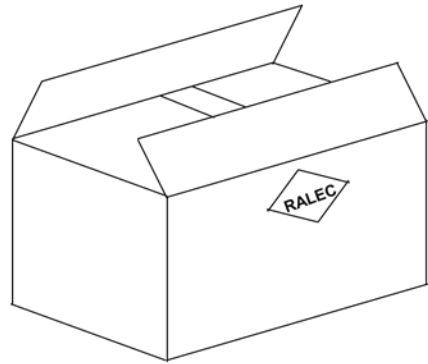
11.7 Inner Box

Reel Number	D Dimension (mm)
1	12
2	24
3	36
4	48
5	60
6	72
7	84
8	96
9	108
10	120



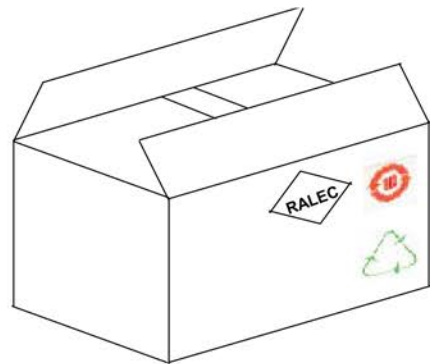
11.8 Box

10R Inner Box Number	L(mm)	W(mm)	D(mm)
2	272	205	210
4	375	280	210
8	544	380	210



11.9 Box (For China)

10R Inner Box Number	L(mm)	W(mm)	D(mm)
2	272	205	210
4	375	280	210
8	544	380	210





12 Measurement Point

背面電極量測		Unit : mm	
TYPE	DIM	A	B
		RTX02	0.80 ± 0.05
RTX03	1.35 ± 0.05	0.35 ± 0.05	
RTX05	1.80 ± 0.05	0.34 ± 0.05	
RTX06	2.90 ± 0.05	0.35 ± 0.05	
RTX12	2.90 ± 0.05	0.35 ± 0.05	
RTX20	4.50 ± 0.05	1.15 ± 0.05	
RTX25	5.90 ± 0.05	1.60 ± 0.05	

13 Stock period

13.1 The temperature condition must be controlled at $25 \pm 5 \text{ }^\circ\text{C}$, the R.H. must be controlled at $60 \pm 15\%$. The stock can maintain quality level in two years.

14 The carton packaged for electronic-information products is made by the symbol as follows: (For china)

	
Marking for control of pollution cause by electronic-information products	Marking for package recovery

15 For this part. It does not use the materials that include the substances specified in RoHS , the detail refer to the part of prohibition or exclusion items in RoHS (2002/95/EC).

1. Cadmium and cadmium compounds (permissive content <math>< 100 \text{ ppm}</math>)
2. Lead and lead compounds (permissive content <math>< 1000 \text{ ppm}</math>)

Exceptions specified:

- (1). Lead contained in the glass of cathode ray tubes, electronic components and fluorescent tubes.
- (2). The glass material used in the electronic components, which includes resistor elements, conductive pastes (silver or copper ones), adhesives, glass frit and sealing materials.

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- (3). Mercury and its mercury compounds (*permissive content <100 ppm*)
- (4). Hexavalent chromium compounds (*permissive content <100 ppm*)
- (5). Polybrominated biphenyls (PBB) (*permissive content <100 ppm*)
- (6). Polybrominated diphenylethers (PBDE) (*permissive content <100 ppm*)

16 Attachments

16.1 Document Revise Record Paper